



## PNP SILICON EPITAXIAL PLANAR TRANSISTORS

TO-92 Plastic Package

BC556\_BC560



## For switching and AF amplifier application

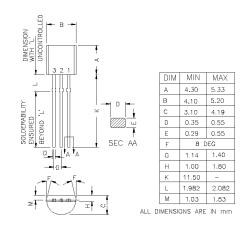
## ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub>=25<sup>o</sup>C unless specified otherwise)

SYMBOL	BC556	BC557	BC560	BC558	BC559	UNITS
V <sub>CBO</sub>	80	50	)	3	0	V
V <sub>CEO</sub>	65	45	5	3	0	V
V <sub>EBO</sub>			5			V
I <sub>C</sub>			100			mA
I <sub>CM</sub>			200			mA
P <sub>tot</sub>	500				mW	
T <sub>stg</sub>	- 65 to +150					°C
Tj			150			°C
	V <sub>CBO</sub> V <sub>CEO</sub> V <sub>EBO</sub> I <sub>C</sub> I <sub>CM</sub> P <sub>tot</sub>	V <sub>CBO</sub> 80   V <sub>CEO</sub> 65   V <sub>EBO</sub> I   I <sub>C</sub> I   P <sub>tot</sub> I	V <sub>CBO</sub> 80 50   V <sub>CEO</sub> 65 45   V <sub>EBO</sub> I I   I <sub>C</sub> I I   P <sub>tot</sub> I I	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

## Characteristics at Ta = 25°C

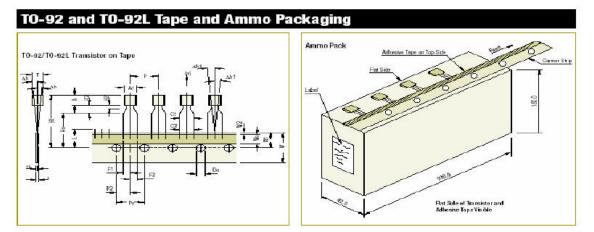
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
DC Current Gain	h <sub>FE</sub>	I <sub>C</sub> =2mA, V <sub>CE</sub> =5V A B C	75 110 200 420	800 220 450 800	-
Collector Emitter Saturation Voltage	V <sub>CE(Sat)</sub>	$I_{C}$ =10mA, $I_{B}$ =0.5mA $I_{C}$ =100mA, $I_{B}$ =5mA	-	0.30	V V
Base Emitter on Voltage	$V_{\text{BE(on)}}$	I <sub>C</sub> =2mA, V <sub>CE</sub> =5V I <sub>C</sub> =10mA, V <sub>CE</sub> =5V	0.55 -	0.75 0.82	V V
Collector Base Cut off Current	I <sub>CBO</sub>	$V_{CB}=30V, I_{E}=0$	-	15	nA
Emitter Base Cut off Current	I <sub>EBO</sub>	V <sub>EB</sub> =5V	-	100	nA
Collector Base Breakdown Voltage BC556 BC557 , BC560 BC558 , BC559	V <sub>(BR)CBO</sub>	I <sub>C</sub> =100μΑ	80 50 30	- - -	V
Collector Emitter Breakdown Voltage BC556 BC557 , BC560 BC558 , BC559	$V_{(BR)CEO}$	I <sub>C</sub> =2mA	65 45 30	- - -	V
Emitter Base Breakdown Voltage	$V_{(BR)EBO}$	I <sub>E</sub> =100μA	5	-	V
Transition Frequency	f <sub>T</sub>		100	-	MHz
Collector Base Capacitance	C <sub>cb</sub>	V <sub>CB</sub> =10V, f=1MHz	-	6.0	pF

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# **Packaging Specifications**

Package / Case Type Packagi	Packaging Type	Std. Packing		Inner Carton		Outer Carton			
		Qty	Qty	\$ize L x W x H	Gross Weight	Qty	Size L x W x H	Gross Weight	
				(cm)	(Kg)		(cm)	(Kg)	
	Bulk	1,000	9K	19 x 19 x 8	1.1	80K	43 x 40 x 35	20.0	
	T&A	2,000	2K	32 x 4.5 x 20	0.7	40K	43 x 40 x 35	15.2	



## **Tape Specifications**

		T0-92			T0-92L				
Item description	Symbol	Min	Nom	Max	Tol	Min	Nom	Max	Tol
Body width	A1	4.45		5.20		4.7		5.1	
Body height	A	4.32		5.33		7.8		8.2	
Body thickness	T	3.18		4.19		3.7		4.1	
Pitch of component <sup>Cr</sup>	P		12.7		±1.0	0	12.7		±0.3
Feed hole pitch <sup>51</sup>	Po	1	12.7	2	±0.3		12.7		±0.2
Feed hole center to component centre <sup>52</sup>	P2		6.35		±0.4		6.35		±0.3
Comp. alignment, Side view <sup>\$3</sup>	Dh		0	1.0			0		±1.0
Comp. alignment, Front view <sup>63</sup>	Dhit		0	1.3		13 -	0		±1.0
Tape width <sup>or</sup>	W	5. S	18	2	±0.5		18.0		+1.0 -0.5
Hold down tape width <sup>or</sup>	Wo		6		±0.2		6.0		±0.5
Hole position	Wit		9	6	+0.7 -0.5		9.0		±0.5
Hold-down tape position	W2	0.0		0.7				1.0	
Load wire clinck height	Ho	1	16	3	±0.5		16.0		±0.5
Component height	H1			24.0				29.0	
Length of snipped leads	L			11.0			1	11.0	
Feed hole diameter <sup>or</sup>	Do	§	4	12	±0.2		4.0		±0.2
Total tape thickness <sup>54</sup>	t			1.2			0.2		±0.5
Lead-to-lead distance <sup>Cr</sup>	F1, F2	2.4		2.7	1	2.2		2.8	
Stand off	H2	0.45		1.45		0.45		1.45	
Clinch height	H3	2		3.0				4.0	
Lead parallelismCr	C1-Gz	-		0.ZZ				0.22	
Pull-out force	(p)	6N				GN			

#### cification

- rn alignment deviation between of to be greater than 0.20 mm.
- um non-cumulative variation n tape feed holes shal not exceed 20 pitches.
- win tape not to exceed beyond the carrier tape and there shall be no re of adhesive.
- e than 3 consecutive missing rents is permitted.
- trailer, having at least three less is required after the last
- ient. shall not interfere with the et feed holes.
- tive pitch error 1.0 mm/20 pitch. easured at bottom of clinch.
- body.
- 0.5 mm Cr Critical Dimension.

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Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

## Disclaimer

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